Title (en)

DEVICE AND METHOD FOR PRODUCING THICK-WALLED PLASTIC MOLDED PARTS HAVING REDUCED SHRINKAGE SITES BY INJECTION MOLDING OR EMBOSSING

Title (de)

VORRICHTUNG UND VERFAHREN ZUR HERSTELLUNG DICKWANDIGER KUNSTSTOFFFORMTEILE MIT VERRINGERTEN EINFALLSTELLEN DURCH SPRITZGIESSEN ODER PRÄGEN

Title (fr)

DISPOSITIF ET PROCÉDÉ DE FABRICATION DE PIÈCES MOULÉES EN PLASTIQUE À PAROI ÉPAISSE PRÉSENTANT UNE RÉDUCTION DES DÉPRESSIONS EN SURFACE, PAR MOULAGE PAR INJECTION OU INJECTION-COMPRESSION

Publication

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Application

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Abstract (en)

[origin: CA2768052A1] The invention relates to a device and method for producing thick-walled plastic molded parts by injection molding or embossing. The device comprises a mold for injection molding or embossing, having a cavity, and is characterized in that the mold comprises a wall region adjacent to the cavity, and a body removed from the cavity and adjacent to the wall region near the cavity, wherein the body of the mold is designed for a temperature T1 and the wall region is designed for a temperature T2 different from the temperature T1. According to the method, the temperature T2 of the wall region of the mold near the cavity is brought to and held at a value greater than the Vicat temperature Tv of the plastic molding mass before and/or during the injection process, wherein the temperature T2 is greater than the temperature T1 of the mold body, and the temperature T2 of the wall region near the cavity is brought to a temperature below the Vicat temperature Tv of the plastic molding mass during the solidification of the plastic molding mass. The result is thick-walled molded plastic parts, such as optical lenses and the like, having reduced shrinkage sites.

IPC 8 full level

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